

### **Technical Data Sheet**

### MODEL NO: 776RGB4B-GH

3528 Package 3.5\*2.8mm RGB Top LEDs

Features:

•Package in 8mm tape on 7" diameter reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

Applications:

Indicators

•Automotive : backlighting in dashboard and switch

•Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP/GaAs	Orange	
InGaN	Green	White Diffuse
InGaN	Blue	

### Electrical/Optical Characteristics(Ta= $25^{\circ}$ C)

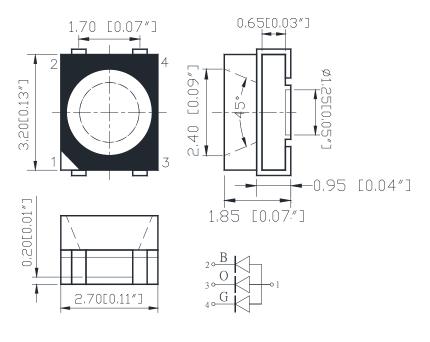
Parameter	Test	Symbol		Value			Unit
	Condition	Symbol	Min	Тур	Max	- Unit	
Dominant wavelength	IF=20mA	λD	0	615	622	630	nm
			G	515	520	525	
			В	460	465	470	
Spectral half bandwidth	IF=20mA	$ riangle \lambda$	0		19		nm
			G		33		
			В		24		
Forward voltage	IF=20mA	VF	0	1.7	2.0	2.5	V
			G	2.8	3.1	3.7	
			В	2.8	3.1	3.7	
	IF=20mA	lv	0	160	320	500	mcd
Luminous intensity			G	630	1200	2000	
			В	160	200	400	
Viewing angle at 50% Iv	IF=10mA	2 <i> </i> $ heta$ 1/2			120		Deg
Reverse current	Vr=5V	lr				10	μΑ



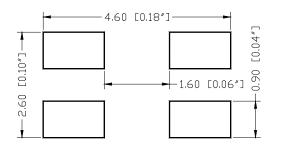
### Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value	Unit
	0	75	
Power dissipation	Pd G	111	mW
	В	111	
Forward current	lf	30	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-20 ~+80	°C
Storage temperature range	Tstg	-40 ~+80	°C
Peak pulsing current (1/10 duty f=1kHz)	IFP	125	mA

## PACKAGING DIMENSIONS (mm):



### **RECOMMEND PAD LAYOUT**



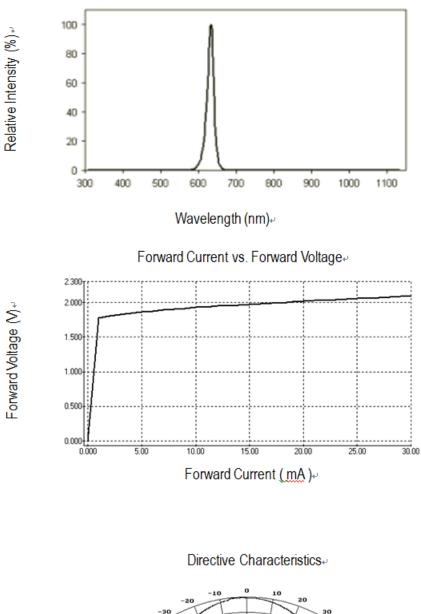
Notes: All dimensions are in millimeters (inches);

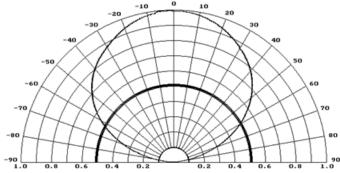
Tolerances are  $\pm 0.2$ mm(0.008inch) unless otherwise noted



## OPTICAL CHARACTERISTIC CURVES (Orange)

Relative Intensity vs. Wavelength-

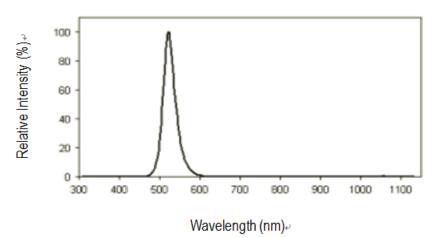




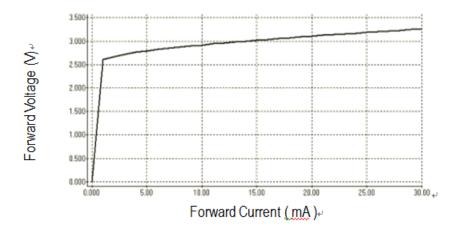


## OPTICAL CHARACTERISTIC CURVES (Green)

Relative Intensity vs. Wavelength-

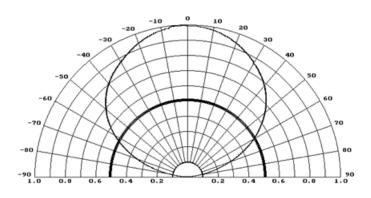


Forward Current vs. Forward Voltage+



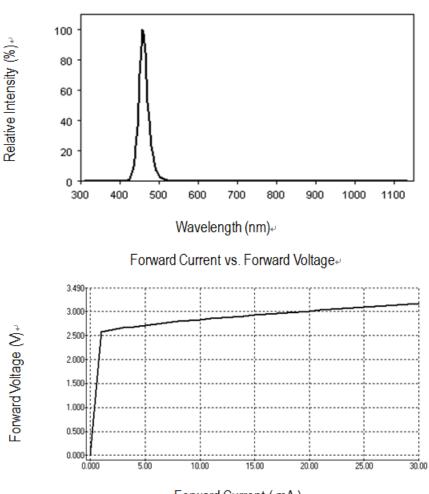
Directive Characteristics.

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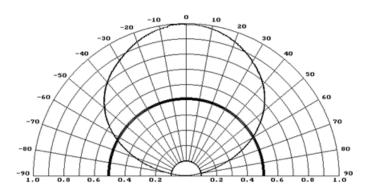
### OPTICAL CHARACTERISTIC CURVES (Blue)



Relative Intensity vs. Wavelength+

Forward Current (mA)+

#### Directive Characteristics.





### **Precautions For Use :**

### **Over - current - proof**

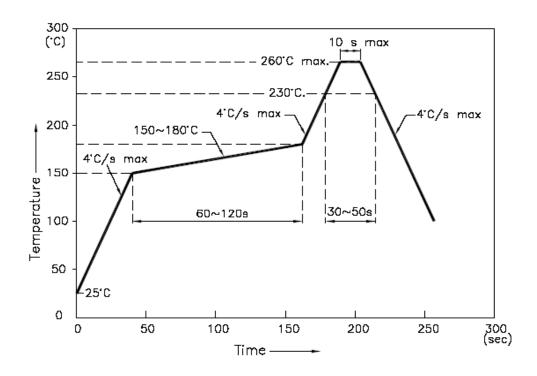
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

#### Storage

1. The operation of temperature and R.H. are  $: 5^{\circ}$ C  $\sim 30^{\circ}$ C,  $60^{\circ}$ R.H. Max.

- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}C\pm5^{\circ}C$  for 15 hrs.

■ Reflow Temp/Time



### NOTES:

- 1. We recommend the reflow temperature  $245^{\circ}C(\pm 5^{\circ}C)$ .the maximum soldering temperature should be limited to  $260^{\circ}C$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

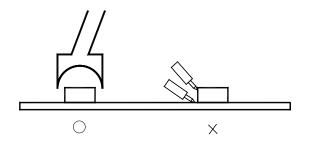


### ■Soldering iron

Basic spec is  $\leq 5$ sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

### ■Rework

- 1. Customer must finish rework within 5 sec under  $260^{\circ}$ C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.